

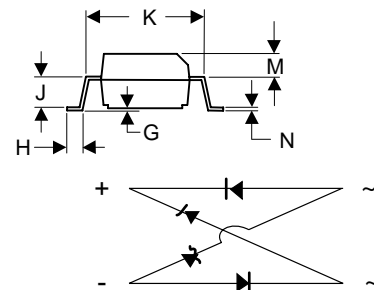
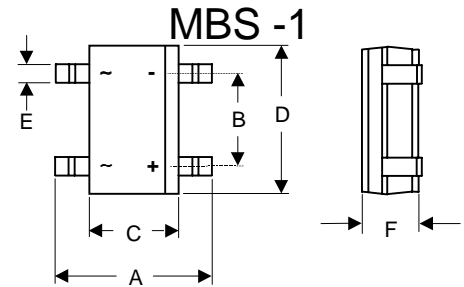
Features

- High Temperature Soldering Guaranteed:260°C/10 Second
- Saves Space On Printed Circuit Board

Mechanical Data

- Lead Free Finish/RoHS Compliant (NOTE 1)("P" Suffix designates RoHS Compliant. See ordering information)
- Case Material:Molded Plastic. UL Flammability Classification Rating 94V-0 and MSL Rating 1
- Terminals: Plated leads Solderable per MIL-STD-750,Method 2026
- Moisture Sensitivity:Level 1 per J-STD-020C

MCC Part Number	Device Marking	Maximum Recurrent Peak Reverse Voltage	Maximum RMS Voltage	Maximum DC Blocking Voltage
MB12S	MB12S	20V	14V	20V
MB14S	MB14S	40V	28V	40V
MB16S	MB16S	60V	42V	60V
MB18S	MB18S	80V	56V	80V
MB110S	MB110S	100V	70V	100V



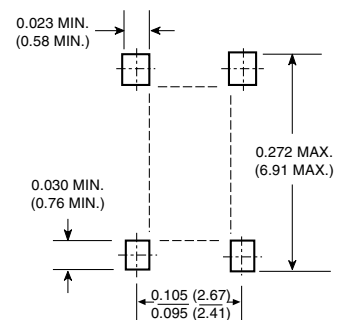
Case Style

Electrical Characteristics @ 25°C Unless Otherwise Specified

Average Forward Current	$I_{F(AV)}$	1A	
Peak Forward Surge Current	I_{FSM}	30A	8.3ms, half sine
Maximum Instantaneous Forward Voltage MB12S-MB14S MB16S MB18S-MB110S	V_F	0.50V 0.70V 0.85V	$I_{FM} = 1A;$ $T_A = 25^{\circ}C$
Maximum DC Reverse Current At Rated DC Blocking Voltage	I_R	0.5mA 20mA	$T_A = 25^{\circ}C$ $T_A = 100^{\circ}C$
Typical Thermal Resistance	R_{thJA} R_{thJL}	$88^{\circ}C/W^{(2)}$ $28^{\circ}C/W^{(2)}$	per leg
Operating Junction and Storage Temperature Range	T_J T_{STG}	-55 to +150 $^{\circ}C$	

DIM	DIMENSIONS				NOTE
	INC HES		MM		
	MIN	MAX	MIN	MAX	
A	.252	.275	6.40	7.00	
B	.095	.106	2.41	2.70	
C	.150	.165	3.80	4.20	
D	.179	.195	4.55	4.95	
E	.019	.031	0.50	0.80	
F	.090	.106	2.30	2.70	
G	.004	.008	0.10	0.20	
H	.027	.043	0.70	1.10	
J	.058	.062	1.47	1.57	
K	.195	.205	4.95	5.21	
M	.039	.049	0.99	1.24	
N	.006	.016	0.15	0.41	

Mounting Pad Layout



- Notes:
1. High Temperature Solder Exemption Applied, see EU Directive Annex Notes 7
 2. Thermal resistance from junction to ambient and from junction to lead P.C.B. mounted on 0.2*0.2"(5.0*5.0mm) copper pad areas.

Fig.1 Forward Current Derating Curve

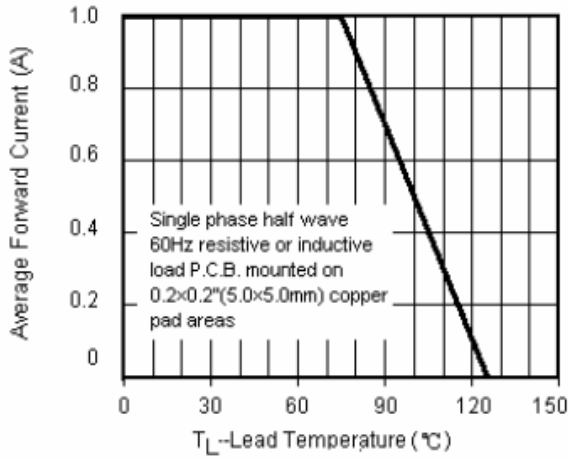


Fig.2 Maximum Non-Repetitive Peak Forward Surge Current

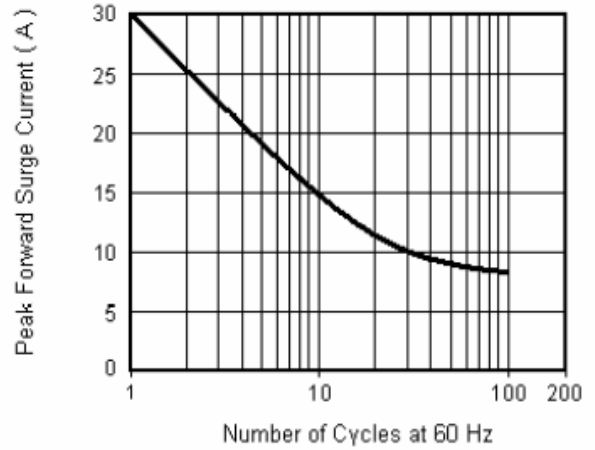


Fig.3 Typical Instantaneous Forward Characteristics

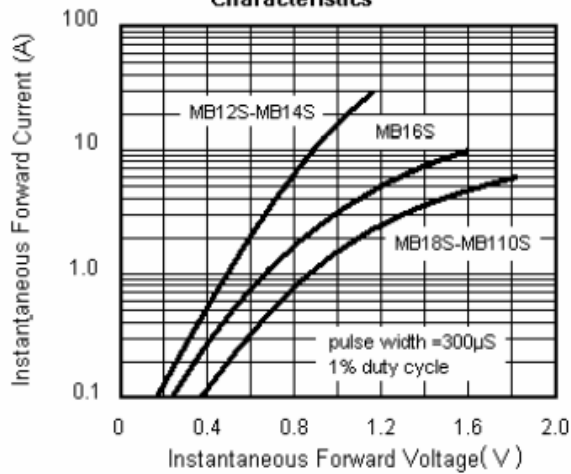


Fig.4 Typical Junction Capacitance

